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# Homogeneous electrochemical deposition of in on a Cu-covered Mo substrate for fabrication of efficient solar cells with a CuInS<sub>2</sub> photoabsorber

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### ABSTRACT

Electrochemical deposition of indium (In) on a copper-covered molybdenum-coated glass substrate from several acidic InCl<sub>3</sub> solutions was studied for fabrication of CuInS<sub>2</sub>-based solar cells. When In was deposited using a simple acidic InCl<sub>3</sub> solution at -0.80 V (*vs.* Ag/AgCl), island-shaped growth was observed, whereas a homogeneous In film was obtained from InCl<sub>3</sub> solution containing citric acid and sodium citrate at -0.98 V (*vs.* Ag/AgCl). Electrochemical and structural analyses revealed that the citric acid additive had a function for smoothing the surface of the In deposit. The mixing with sodium citrate induced appreciable inhibition of H<sub>2</sub> evolution during the In deposition, leading to high current efficiency of >90%. The CuInS<sub>2</sub> film derived from the homogeneous In had a uniform thickness with a smooth surface, while the CuInS<sub>2</sub> film obtained from the island-shaped In deposit showed a large variation in thickness with recessed areas. The CuInS<sub>2</sub> film derived from the homogeneous In was showed better photoelectrochemical response than that of the film fabricated from the island-shaped In. As expected from these differences, the solar cell with an Al:ZnO/CdS/CuInS<sub>2</sub>/Mo structure derived from the homogeneous In film showed the best conversion efficiency of 7.8% with relatively high reproducibility.

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#### 1. Introduction

Copper indium disulfide (CuInS<sub>2</sub>) is a ternary semiconductor compound that has been studied as an absorber for thin film solar cells, due to its optimal band gap value for sunlight radiation (1.5 eV) [1], sufficiently large absorption coefficient of  $3 \times 10^5 \text{ cm}^{-1}$ below 1000 nm [2], and efficient carrier mobility (2-20 cm<sup>2</sup> v<sup>-1</sup> s<sup>-1</sup>) [3,4]. The ideal substrate solar cell consisting of stacked layers of the CuInS<sub>2</sub> film, a thin buffer, and transparent conductive oxide (TCO) on a Mo-coated glass (Mo/glass) substrate showed highest efficiency of 11.4% [5,6]. The CuInS<sub>2</sub> absorber in a solar cell is typically prepared by sequential deposition of Cu and In metallic layers (*i.e.*, a Cu/In bilayer) on the Mo/glass substrate by vacuum methods such as sputtering and evaporation [7–9], followed by sulfurization [5–11]. However, the use of these vacuum methods leads to high equipment cost and significant losses of raw materials [12]. In order to lower electricity-generating costs of solar cells to a level competitive with commercial electricity generation, replacements of these vacuum methods with facile non-vacuum methods are promising. Hence, several non-vacuum methods, such as spraying [13-16] and electrochemical deposition [17-27], have been reported in the literature.

Among the above-mentioned non-vacuum methods, electrochemical deposition of the CuInS<sub>2</sub> film has been shown to be desirable because of its advantages, including low equipment cost, negligible waste of chemicals with utilization efficiencies close to 100%, possible formation of a compact film required for solar cell application, scalability, and manufacturability of a large-area polycrystalline film. For CuInS<sub>2</sub> film deposition, a sequential route consisting of electrochemical deposition of a Cu/In bilayer followed by sulfurization has been applied as the most usual process [19-27]. In this process, the latter sulfurization step is performed by using H<sub>2</sub>S gas or sulfur vapor in much the same way as the abovementioned sputtering technique. Very recently, a solar cell based on electrochemically fabricated CuInS<sub>2</sub> films has achieved conversion efficiency close to that of a cell fabricated by the vacuum process (11%) [27], indicating that the electrochemical deposition method has sufficient potential for future practical applications. For the further improvement of the conversion efficiency of the solar cell based on the electrochemically prepared CuInS<sub>2</sub> film, there is room for optimizing structures of metal staked precursors.

One of the critical problems of electrochemical deposition of a Cu/In film is the difficulty in obtaining a homogeneous In layer, *i.e.*, the In layer tends to form an island-shaped morphology using typical electrochemical deposition solutions based on both chloride and sulfate solutions [28,29]. The In island formation would be detrimental because of inductions of thickness and composition variations of resulting CuInS<sub>2</sub> films. Kinetic and mechanistic studies have shown that uncontrollable nucleation and growth of

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In metal in such simple deposition solutions induced the formation of In islands [28,29]. These facts have motivated us to find an electrochemical deposition condition to form a flat and homogeneous In layer on the Cu-deposited Mo/glass substrate. In order to achieve this objective, we focused on evaluation of the effects of organic additives on surface morphology of the thus-obtained In layer. In this study, we employed citric acid and sodium citrate as ideal organic additives to fabricate Cu/In bilayers in homogeneous In distributions. Effects of the different Cu/In film morphologies on structural, photoelectrochemical, and photovoltaic properties of the CuInS<sub>2</sub> films obtained from these Cu/In bilayers were also studied.

#### 2. Experimental

A Mo/glass substrate with sheet resistance of *ca*. 20  $\Omega$ /square was used as a cathode for the electrochemical deposition of Cu/In bilayers. Before the deposition, the Mo/glass substrate was precleaned by sonication in acetone, followed by immersion in 25 vol% ammonia solution for 5 min to remove the molybdenum oxide layer  $(MoO_x)$  on the surface [30]. Cu/In bilayers were deposited successively on the Mo/glass substrate by using a common threeelectrode cell with a Pt foil as a counter electrode and an Ag/AgCl reference electrode under potentiostatic control using a Hokuto Denko HSV-100 potentiostat-galvanostat. Temperature of all the deposition solutions was kept at  $24 \pm 1$  °C by immersion in a thermostated water bath. Deposition of the Cu layer was performed at -0.4V (vs. Ag/AgCl) in an aqueous solution containing  $10 \text{ mmol dm}^{-3} \text{ CuSO}_4$  and  $10 \text{ mmol dm}^{-3}$  citric acid (pH 2.3) [26]. The amount of deposited Cu metal was controlled by the total electric charge at 0.83 C cm<sup>-2</sup> using a Hokuto Denko HF-201A coulomb/ampere hour meter. For deposition of the In layer onto the top of the Cu-deposited Mo/glass (Cu/Mo/glass), three kinds of acidic solutions with pH adjusted to 2.2 by a concentrated HCl solution were used in this study: one was a  $12 \text{ mmol dm}^{-3} \text{ InCl}_3$ solution (In-bath(A)) [26], another was a 30 mmol  $dm^{-3}$  InCl<sub>3</sub> solution containing 10 mmol dm<sup>-3</sup> citric acid (In-bath(B)), and the other consisted of 30 mmol dm<sup>-3</sup> InCl<sub>3</sub>, 10 mmol dm<sup>-3</sup> citric acid, and 35 mmol dm<sup>-3</sup> sodium citrate (In-bath(C)) [31]. Applied potentials for the In deposition were adjusted to -0.80 V (vs. Ag/AgCl) for Inbath(A) and -0.98 V (vs. Ag/AgCl) for In-bath(B) and In-bath(C). The total charge during the In deposition was fixed at 0.96 C cm<sup>-2</sup>, irrespective of the kind of In solution used. Amounts of deposited In metals thus-formed were quantified by measuring the changes in weights of the Cu/Mo/glass substrates before and after In deposition. As separate experiments, contributions of H<sub>2</sub> evolution during the In deposition were studied using aqueous HCl solutions (pH 2.2) containing 10 mmol dm<sup>-3</sup> citric acid and containing 10 mmol dm<sup>-3</sup> citric acid and 35 mmol dm<sup>-3</sup> sodium citrate (see below).

Sulfurization of as-prepared Cu/In bilayer films to form CuInS<sub>2</sub> films was performed by using a three-step temperature profile as reported previously [26], with slight modifications. First, the Cu/In bilayer films were heated to 110 °C in Ar, and then heating at this temperature was continued for 60 min. In the second step, the film treated at 110 °C was heated to 520 °C in Ar using a heating ramp of 25 °C min<sup>-1</sup>. Finally, sulfurization of the film was performed by introduction of H<sub>2</sub>S (5% in Ar) at 520 °C for 10 min, and then the film was allowed to cool down to ambient temperature in Ar or H<sub>2</sub>S (5% in Ar). Since all of the Cu/In bilayer films had relatively Cu-rich compositions, the CuINS<sub>2</sub> films thus-formed include a Cu<sub>x</sub>S impurity component: these films were treated with a 10% KCN solution to remove the Cu<sub>x</sub>S component [5].

Surface and cross-sectional morphologies of the Cu, Cu/In, and CuInS<sub>2</sub> films prepared were examined using a Hitachi S-5000 FEG scanning electron microscope (SEM). X-ray diffraction (XRD)



Fig. 1. A top view SEM image of an electrochemically deposited Cu film. Inset shows the corresponding cross-sectional image.

patterns were measured using a Rigaku MiniFlex X-ray diffractometer (Cu K $\alpha$ , Ni filter).

Photoelectrochemical properties of CuInS<sub>2</sub> films were measured in an aqueous solution containing 0.1 mmol dm<sup>-3</sup> Eu(NO<sub>3</sub>)<sub>3</sub> as an electron acceptor at pH 4. A Pyrex electrolytic cell having a flat window was used. The photocurrent response of the film was measured under potentiostatic control using a three-electrode system with a Pt foil counter electrode and an Ag/AgCl reference electrode. Transient photocurrents at potentials ranging from 0.2 V to -0.45 V (*vs.* Ag/AgCl) were measured using the lock-in technique under chopped illumination of 600 nm monochromatic light. Photocurrent external quantum efficiency (EQE) spectra at the potential of -0.4 V (*vs.* Ag/AgCl) were also measured using the lock-in technique under chopped illumination of monochromatic light (400–900 nm). The number of incident photons was determined by an OPHIR Orion Laser power meter equipped with a photodiode. All the photoelectrochemical measurements were performed under N<sub>2</sub> purging.

For evaluation of solar cell properties of the CuInS<sub>2</sub> films, the films were processed to form an Al:ZnO/CdS/CIS/Mo/glass structure. On the CuInS<sub>2</sub> films, a CdS buffer layer was deposited by chemical bath deposition (CBD) [26], and an Al:ZnO window layer was then deposited on the top of the CdS layer by radio frequency (RF) magnetron sputtering [26,32]. Current density–voltage (J–V) characteristics under simulated AM1.5 irradiation (100 mW cm<sup>-2</sup>) through the Al:ZnO window layer and those under dark of thus-obtained solar cells were measured with a Bunkoh–Keiki CEP–015 photovoltaic measurement system.

#### 3. Results and discussion

#### 3.1. Effects of additives for In deposition

Fig. 1 shows a typical SEM image of the Cu film on Mo/glass. The top view image shows that the surface of the film has a rugged morphology composed of small lumps of several hundred nanometers in size. The corresponding cross-sectional image of the Cu film shown in inset of Fig. 1 shows the formation of a condensed film at the bottom layer with a thickness of *ca.* 250 nm, while the upper part has a bumpy structure, as expected from the surface morphology. Since there is no appreciable crack or pinhole in the Cu film, we employed this film as the substrate (*i.e.*, the Cu/Mo/glass substrate) for successive electrochemical deposition of In. Results

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